

Global Semiconductor Assembly Equipment Market 2017 Share, Trend, Segmentation and Forecast To 2021

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[Semiconductor Assembly Equipment Market 2017](#)

Global Semiconductor Assembly Equipment market competition by top manufacturers, with production, price, revenue (value) and market share for each manufacturer; the top players including

Applied Materials
ASM Pacific Technology
Kulicke & Soffa Industries
Palomar Technologies
Tokyo Seimitsu
BE Semiconductor Industries
Greatek Electronics
Hesse Mechatronics
HYBOND, Inc
West Bond
Shinkawa
Toray Engineering
ChipMOS Technologies
DIAS Automation



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Geographically, this report is segmented into several key Regions, with production, consumption, revenue (million USD), market share and growth rate of Semiconductor Assembly Equipment in these regions, from 2012 to 2022 (forecast), covering

North America
Europe
China
Japan
Southeast Asia

India

On the basis of product, this report displays the production, revenue, price, market share and growth rate of each type, primarily split into

Die Bonding Equipment
Inspection and Dicing Equipment
Packaging Equipment
Wire Bonding Equipment
Plating Equipment
Other

On the basis on the end users/applications, this report focuses on the status and outlook for major applications/end users, consumption (sales), market share and growth rate of

Semiconductor Assembly Equipment for each application, including
Integrated Device Manufacturer (IDMs)
Outsourced Semiconductor Assembly and Testing (OSATs)

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